Zener Transient Voltage Suppressors

GENERAL DATA IS APPLICABLE TO ALL SERIES IN THIS GROUP

The SMB series is designed to protect voltage sensitive components from high voltage, high energy transients. They have excellent clamping capability, high surge capability, low zener impedance and fast response time. The SMB series is supplied in ON Semiconductor's exclusive, cost-effective, highly reliable Surmetic package and is ideally suited for use in communication systems, numerical controls, process controls, medical equipment, business machines, power supplies and many other industrial/consumer applications.

Specification Features:

- Standard Zener Breakdown Voltage Range 6.4 to 200 V
- Stand-off Voltage Range 5 to 170 V
- Peak Power 600 Watts @ 1 ms
- Maximum Clamp Voltage @ Peak Pulse Current
- Low Leakage < 5 μA Above 10 V
- UL Recognition
- Response Time is Typically < 1 ns

Mechanical Characteristics:

CASE: Void-free, transfer-molded, thermosetting plastic

FINISH: All external surfaces are corrosion resistant and leads are readily solderable

readily solderable

POLARITY: Cathode indicated by molded polarity notch. When operated in zener mode, will be positive with respect to anode

MOUNTING POSITION: Any

LEADS: Modified L—Bend providing more contact area to bond pad **MAXIMUM CASE TEMPERATURE FOR SOLDERING PURPOSES:**

260°C for 10 Seconds

WAFER FAB LOCATION: Phoenix, Arizona

ASSEMBLY/TEST LOCATION: Seremban, Malaysia



ON Semiconductor

Formerly a Division of Motorola

http://onsemi.com

PLASTIC SURFACE MOUNT ZENER OVERVOLTAGE TRANSIENT SUPPRESSORS 5.0–170 VOLTS 600 WATT PEAK POWER



SMB PLASTIC CASE 403A

ORDERING INFORMATION

Device	Package	Shipping
SMBXXXAT3	SMB	Tape and Reel 2500 Units/Reel

Devices listed in *bold, italic* are ON Semiconductor **Preferred** devices. **Preferred** devices are recommended choices for future use and best overall value.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Power Dissipation (1) @ T _L ≤ 25°C	P _{PK}	600	Watts
Forward Surge Current (2) @ T _A = 25°C	^I FSM	100	Amps
Thermal Resistance from Junction to Lead (typical)	$R_{ heta JL}$	25	°C/W
Operating and Storage Temperature Range	Т _Ј , Т _{stg}	- 55 to +150	°C

NOTES: 1. Nonrepetitive current pulse per Figure 2 and derated above $T_A = 25$ °C per Figure 3.

2. 1/2 sine wave (or equivalent square wave), PW = 8.3 ms, duty cycle = 4 pulses per minute maximum.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted).

		Breakdow	n Voltage*		Peak	Maximum	
	Reverse Stand-Off Voltage	V _{BR}	<u>@</u> Һ	Maximum Clamping Voltage	Pulse Current (See Figure 2)	Reverse Leakage @ V _R	
Device††	V _R Volts (1)	Volts Min	mA	V _C @ I _{pp}	I _{pp} † Amps	IR μ A	Device Marking
1SMB5.0AT3	5.0	6.40	10	9.2	65.2	μ Α 800	KE
1SMB6.0AT3 1SMB6.5AT3	6.0 6.5	6.67 7.22	10 10	10.3 11.2	58.3 53.6	800 500	KG KK
1SMB7.0AT3	7.0	7.78	10	12.0	50.0	200	KM
1SMB7.5AT3	7.5	8.33	1.0	12.9	46.5	100	KP
1SMB8.0AT3 1SMB8.5AT3	8.0 8.5	8.89 9.44	1.0 1.0	13.6 14.4	44.1 41.7	50 10	KR KT
1SMB9.0AT3	9.0	10.0	1.0	15.4	39.0	5.0	KV
1SMB10AT3 1SMB11AT3	10 11	11.1 12.2	1.0 1.0	17.0 18.2	35.3 33.0	5.0 5.0	KX KZ
1SMB11AT3	12	13.3	1.0	19.9	30.2	5.0	LE
1SMB13AT3	13	14.4	1.0	21.5	27.9	5.0	LG
1SMB14AT3 1SMB15AT3	14 15	15.6 16.7	1.0 1.0	23.2 24.4	25.8 24.0	5.0 5.0	LK LM
1SMB16AT3	16	17.8	1.0	26.0	23.1	5.0	LP
1SMB17AT3	17	18.9	1.0	27.6	21.7	5.0	LR
1SMB18AT3 1SMB20AT3	18 20	20.0 22.2	1.0 1.0	29.2 32.4	20.5 18.5	5.0 5.0	LT LV
1SMB22AT3	22	24.4	1.0	35.5	16.9	5.0	LX
1SMB24AT3 1SMB26AT3	24 26	26.7 28.9	1.0	38.9 42.1	15.4 14.2	5.0 5.0	LZ ME
1SMB28AT3	28	31.1	1.0	42.1 45.4	13.2	5.0	MG
1SMB30AT3 1SMB33AT3	30 33	33.3 36.7	1.0 1.0	48.4 53.3	12.4 11.3	5.0 5.0	MK MM
1SMB36AT3	36	40.0	1.0	58.1	10.3	5.0	MP
1SMB40AT3	40	44.4	1.0	64.5	9.3	5.0	MR
1SMB43AT3 1SMB45AT3	43 45	47.8 50.0	1.0 1.0	69.4 72.7	8.6 8.3	5.0 5.0	MT MV
1SMB48AT3	48	53.3	1.0	77.4	7.7	5.0	MX
1SMB51AT3	51	56.7	1.0	82.4 87.1	7.3	5.0	MZ NE
1SMB54AT3 1SMB58AT3	54 58	60.0 64.4	1.0 1.0	93.6	6.9 6.4	5.0 5.0	NG
1SMB60AT3	60	66.7	1.0	96.8	6.2	5.0	NK
1SMB64AT3 1SMB70AT3	64 70	71.1 77.8	1.0 1.0	103 113	5.8 5.3	5.0 5.0	NM NP
1SMB75AT3	75	83.3	1.0	121	4.9	5.0	NR
1SMB78AT3 1SMB85AT3	78 85	86.7 94.4	1.0 1.0	126 137	4.7 4.4	5.0	NT NV
1SMB85AT3 1SMB90AT3	90	94.4 100	1.0	137 146	4.4 4.1	5.0 5.0	NV NX
1SMB100AT3	100	111	1.0	162	3.7	5.0	NZ
1SMB110AT3 1SMB120AT3	110 120	122 133	1.0 1.0	177 193	3.4 3.1	5.0 5.0	PE PG
1SMB130AT3	130	144	1.0	209	2.9	5.0	PK
1SMB150AT3	150	167	1.0	243	2.5	5.0	PM
1SMB160AT3 1SMB170AT3	160 170	178 189	1.0 1.0	259 275	2.3 2.2	5.0 5.0	PP PR
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Devices listed in bold, italic are ON Semiconductor Preferred devices.

ABBREVIATIONS AND SYMBOLS

٧c

Stand Off Voltage. Applied reverse voltage to assure a V_R

non-conductive condition (See Note 1).

This is the minimum breakdown voltage the device will V_{(BR)min} exhibit and is used to assure that conduction does not

occur prior to this voltage level at 25°C.

Maximum Clamping Voltage. The maximum peak voltage appearing across the transient suppressor when subjected to the peak pusle current in a one millisecond time interval. The peak pulse voltages are the combination of voltage rise due to both the series resistance and

thermal rise.

Peak Pulse Current — See Figure 2

Peak Pulse Power Reverse Leakage

Note 1: A transient suppressor is normally selected according to the reverse "Stand Off Voltage" (VR) which should be equal to or greater than the DC or continuous peak operating voltage level.

 $^{^{\}star}$ VBR measured at pulse test current IT at an ambient temperaure of 25°C.

[†]Surge current waveform per Figure 2 and derate per Figure 3 of the General Data — 600 Watt at the beginning of this group.

^{††}T3 suffix designates tape and reel of 2500 units.

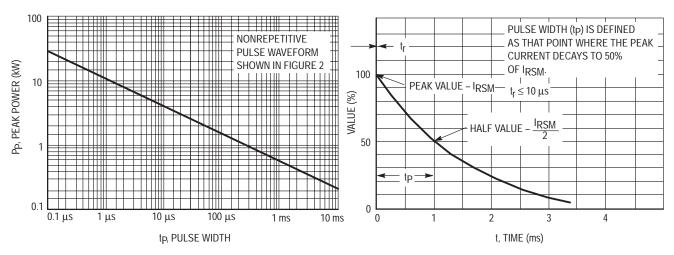


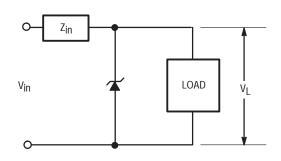
Figure 1. Pulse Rating Curve

PEAK PULSE DERATING IN % OF PEAK POWER OR CURRENT @ $T_A = 25^{\circ}C$ T_A, AMBIENT TEMPERATURE (°C)

Figure 3. Pulse Derating Curve

Figure 2. Pulse Waveform

TYPICAL PROTECTION CIRCUIT



APPLICATION NOTES

RESPONSE TIME

In most applications, the transient suppressor device is placed in parallel with the equipment or component to be protected. In this situation, there is a time delay associated with the capacitance of the device and an overshoot condition associated with the inductance of the device and the inductance of the connection method. The capacitive effect is of minor importance in the parallel protection scheme because it only produces a time delay in the transition from the operating voltage to the clamp voltage as shown in Figure 4.

The inductive effects in the device are due to actual turn-on time (time required for the device to go from zero current to full current) and lead inductance. This inductive effect produces an overshoot in the voltage across the equipment or component being protected as shown in Figure 5. Minimizing this overshoot is very important in the application, since the main purpose for adding a transient suppressor is to clamp voltage spikes. The SMB series have a very good response time, typically < 1 ns and negligible inductance. However, external inductive effects could produce unacceptable overshoot. Proper circuit layout,

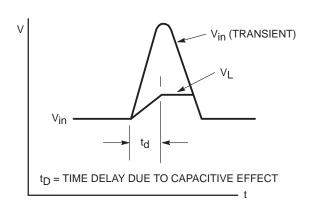
minimum lead lengths and placing the suppressor device as close as possible to the equipment or components to be protected will minimize this overshoot.

Some input impedance represented by Z_{in} is essential to prevent overstress of the protection device. This impedance should be as high as possible, without restricting the circuit operation.

DUTY CYCLE DERATING

The data of Figure 1 applies for non-repetitive conditions and at a lead temperature of 25°C. If the duty cycle increases, the peak power must be reduced as indicated by the curves of Figure 6. Average power must be derated as the lead or ambient temperature rises above 25°C. The average power derating curve normally given on data sheets may be normalized and used for this purpose.

At first glance the derating curves of Figure 6 appear to be in error as the 10 ms pulse has a higher derating factor than the 10 μs pulse. However, when the derating factor for a given pulse of Figure 6 is multiplied by the peak power value of Figure 1 for the same pulse, the results follow the expected trend.



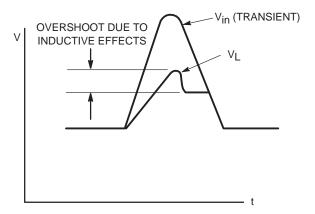


Figure 4. Figure 5.

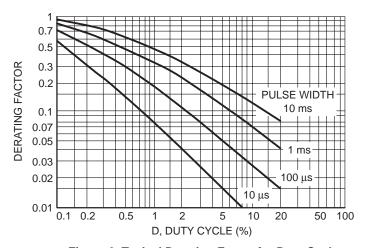


Figure 6. Typical Derating Factor for Duty Cycle

UL RECOGNITION

The entire series has *Underwriters Laboratory Recognition* for the classification of protectors (QVGV2) under the UL standard for safety 497B and File #116110. Many competitors only have one or two devices recognized or have recognition in a non-protective category. Some competitors have no recognition at all. With the UL497B recognition, our parts successfully passed several tests

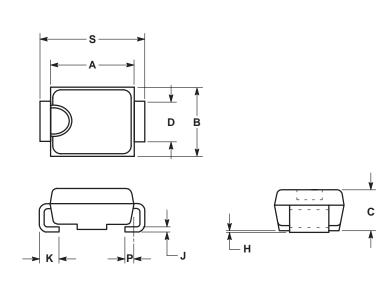
including Strike Voltage Breakdown test, Endurance Conditioning, Temperature test, Dielectric Voltage-Withstand test, Discharge test and several more.

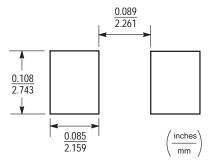
Whereas, some competitors have only passed a flammability test for the package material, we have been recognized for much more to be included in their Protector category.

OUTLINE DIMENSIONS

Transient Voltage Suppressors – Surface Mounted

600 Watt Peak Power





SMB Footprint

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: INCH.

 3. D DIMENSION SHALL BE MEASURED WITHIN DIMENSION P.

	INCI	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.160	0.180	4.06	4.57	
В	0.130	0.150	3.30	3.81	
С	0.075	0.095	1.90	2.41	
D	0.077	0.083	1.96	2.11	
Н	0.0020	0.0060	0.051	0.152	
J	0.006	0.012	0.15	0.30	
K	0.030	0.050	0.76	1.27	
P	0.020 REF		0.51 REF		
S	0.205	0.220	5.21	5.59	

CASE 403A **PLASTIC**

(Refer to Section 10 of the TVS/Zener Data Book (DL150/D) for Surface Mount, Thermal Data and Footprint Information.)



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